

Contents

1	Introduction	1
	Jun So Pak and Joungho Kim	
2	Electrical Modeling of a Through Silicon Via	23
	Joohee Kim, Jun So Pak and Joungho Kim	
3	High-Speed TSV-Based Channel Modeling and Design	61
	Heegon Kim, Jun So Pak and Joungho Kim	
4	Noise Coupling and Shielding in 3D ICs	115
	Jonghyun Cho, Jun So Pak and Joungho Kim	
5	Thermal Effects on TSV Signal Integrity	147
	Manho Lee, Jun So Pak and Joungho Kim	
6	Power Distribution Network Modeling and Analysis for TSV and Interposer-Based 3D-ICs in the Frequency Domain	173
	Kiyeong Kim, Jun So Pak and Joungho Kim	
7	TSV Decoupling Schemes	225
	Eunseok Song, Jun So Pak and Joungho Kim	
	About the Authors.	273
	Index	277

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